

SBAS017C - NOVEMBER 1996 - REVISED OCTOBER 2006

16-Bit 10µs Serial CMOS Sampling ANALOG-TO-DIGITAL CONVERTER

FEATURES

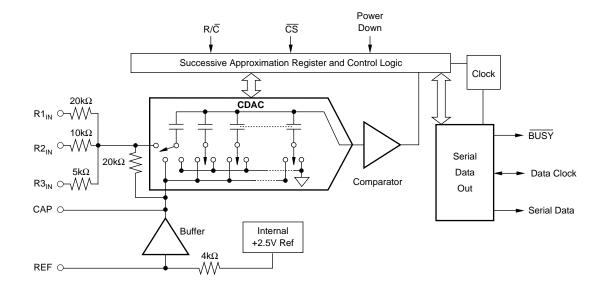
- 100kHz SAMPLING RATE
- 86dB SINAD WITH 20kHz INPUT
- +2LSB INL
- DNL: 16 Bits No Missing Codes
- SIX SPECIFIED INPUT RANGES
- SERIAL OUTPUT
- SINGLE +5V SUPPLY OPERATION
- PIN-COMPATIBLE WITH 12-BIT ADS7808
- USES INTERNAL OR EXTERNAL REFERENCE
- 100mW MAX POWER DISSIPATION
- 0.3" SO-20
- SIMPLE DSP INTERFACE

DESCRIPTION

The ADS7809 is a complete 16-bit sampling Analog-to-Digital (A/D) converter using state-of-the-art CMOS structures. It contains a 16-bit capacitor-based Successive Approximation Register (SAR) A/D converter with sample-and-hold, reference, clock, and a serial data interface. Data can be outputted using the internal clock, or can be synchronized to an external data clock. The ADS7809 also provides an output synchronization pulse for ease of use with standard DSP processors.

The ADS7809 is specified at a 100kHz sampling rate, and specified over the full temperature range. Laser-trimmed scaling resistors provide various input ranges including ±10V and 0V to 5V, while an innovative design operates from a single +5V supply, with power dissipation under 100mW.

The ADS7809 is available in a 0.3" SO-20, and is fully specified for operation over the industrial -40° C to $+85^{\circ}$ C range.





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

All trademarks are the property of their respective owners.



ABSOLUTE MAXIMUM RATINGS(1)

Analog Inputs: R1 _{IN}	+25V
R2 _{IN}	
R3 _{IN}	
REF V _{ANA} + 0.3V to AG	
CAP Indefinite Short	to AGND2,
Momentary S	hort to V _{ANA}
Ground Voltage Differences: DGND, AGND2	±0.3V
V _{ANA}	7V
V _{DIG} to V _{ANA}	+0.3
V _{DIG}	7V
Digital Inputs–0.3V to	$V_{DIG} + 0.3V$
Maximum Junction Temperature	
Internal Power Dissipation	700mW
Lead Temperature (soldering, 10s)	+300°C

NOTE: (1) Stresses above those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. Exposure to absolute maximum conditions for extended periods may affect device reliability.

ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PACKAGE/ORDERING INFORMATION(1)

PRODUCT	MAXIMUM LINEARITY ERROR (LSB)		MINIMUM SIGNAL-TO- (NOISE + DISTORTION) RATIO (dB)	PACKAGE- LEAD	PACKAGE DESIGNATOR	SPECIFIED TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER	TRANSPORT MEDIA, QUANTITY
ADS7809U	±3	15	83	SO-20	DW	-40°C to +85°C	ADS7809U	ADS7809U	Rail, 38
"	"	"	"	"	"	"	"	ADS7809U/1K	Tape and Reel, 1000
ADS7809UB	±2	16	86	"	"	"	ADS7809UB	ADS7809UB	Rail, 38
"	"	"	"	"	"	"	"	ADS7809UB/1K	Tape and Reel, 1000

NOTE: (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

ELECTRICAL CHARACTERISTICS

At $T_A = -40^{\circ}\text{C}$ to +85°C, $f_S = 100\text{kHz}$, $V_{DIG} = V_{ANA} = +5\text{V}$, using internal reference and fixed resistors (see Figure 4), unless otherwise specified.

			ADS7809U	J		ADS7809U	В		
PARAMETER	CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNITS	
RESOLUTION				16			*	Bits	
ANALOG INPUT Voltage Ranges Impedance Capacitance			±10,	0V to 5V, e		ble I)		pF	
THROUGHPUT SPEED Complete Cycle Throughput Rate	Acquire and Convert	100		10	*		*	μs kHz	
DC ACCURACY Integral Linearity Error Differential Linearity Error No Missing Codes Transition Noise ⁽²⁾ Full-Scale Error Grift Full-Scale Error Drift Full-Scale Error Drift Bipolar Zero Error Drift Unipolar Zero Error Drift Unipolar Zero Error Torift Unipolar Zero Error Torift Unipolar Zero Error Drift Unipolar Zero Error Drift Recovery to Rated Accuracy after Power-Down Power-Supply Sensitivity (VDIG = VANA = VD)	Ext. 2.5000V Ref Ext. 2.5000V Ref Ext. 2.5000V Ref Bipolar Ranges Bipolar Ranges OV to 10V Ranges OV to 4V, 0V to 5V Ranges Unipolar Ranges 1μF Capacitor to CAP +4.75V < V _D < +5.25V	15	1.3 ±7 ±2 ±2 ±2 1	±3 +3, -2 ±0.5 ±0.5 ±10 ±5 ±3	16	* * * * *	±2 ±1 * * * *	LSB(1) LSB Bits LSB % ppm/°C % ppm/°C mV ppm/°C mV ppm/°C mV strict stri	
AC ACCURACY Spurious-Free Dynamic Range Total Harmonic Distortion Signal-to-(Noise + Distortion) Signal-to-Noise Full-Power Bandwidth(6)	$\begin{aligned} f_{\text{IN}} &= 20\text{kHz} \\ f_{\text{IN}} &= 20\text{kHz} \\ f_{\text{IN}} &= 20\text{kHz} \\ -60\text{dB Input} \\ f_{\text{IN}} &= 20\text{kHz} \end{aligned}$	90 83 83	100 -100 88 30 88 250	-90	96 86 86	* * * 32 * *	-94	dB ⁽⁵⁾ dB dB dB dB kHz	
SAMPLING DYNAMICS Aperture Delay Transient Response Overvoltage Recovery ⁽⁷⁾	FS Step		40 150	2		*	*	ns µs ns	
REFERENCE Internal Reference Voltage Internal Reference Source Current (Must use external buffer)	No Load	2.48	2.5 1	2.52	*	*	*	V μA	
External Reference Voltage Range For Specified Linearity External Reference Current Drain	Ext. 2.5000V Ref	2.3	2.5	2.7	*	*	*	V μA	
DIGITAL INPUTS Logic Levels V _{IL} V _{IH} (8) I _{IL} I _{IH}	V _{IL} = 0V V _{IH} = 5V	-0.3 +2.0		+0.8 V _D + 0.3V ±10 ±10	*		* * * *	V V μA μA	

ELECTRICAL CHARACTERISTICS (Cont.)

At $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, $f_S = 100\text{kHz}$, $V_{DIG} = V_{ANA} = +5V$, using internal reference and fixed resistors as shown in Figure 4, unless otherwise specified.

			ADS7809U		,	ADS7809UE	3	
PARAMETER	CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
DIGITAL OUTPUTS								
Data Format				Serial	16 bits			
Data Co			Binary Two	o's Complei	ment or Stra	aight Binary		
Pipeline Delay		Conver	sion results	only availa	ble after co	mpleted cor	version.	
Data Clock			Selectable	for internal	or external	data clock		
Internal	EXT/INT LOW		2.3			*		MHz
(Output Only When								
Transmitting Data)								
External	EXT/INT HIGH	0.1		10	*		*	MHz
(Can Run Continually)								
V _{OL}	$I_{SINK} = 1.6mA$			+0.4			*	V
V _{OH}	I _{SOURCE} = 500μA	+4			*			V
Leakage Current	High-Z State,			±5			*	μΑ
	$V_{OUT} = 0V \text{ to } V_{DIG}$							·
Output Capacitance	High-Z State			15			*	pF
POWER SUPPLIES								
Specified Performance								
V _{DIG}	Must be ≤ V _{ANA}	+4.75	+5	+5.25	*	*	*	V
V _{ANA}		+4.75	+5	+5.25	*	*	*	V
I _{DIG}			0.3			*		mA
I _{ANA}			16			*		mA
Power Dissipation: PWRD LOW	$V_{ANA} = V_{DIG} = 5V$, $f_S = 100$ kHz			100			*	mW
PWRD HIGH	J		50			*		μW
TEMPERATURE RANGE								
Specified Performance		-40		+85	*		*	°C
Derated Performance		-55		+125	*		*	°C
Storage		-65		+150	*		*	°C
Thermal Resistance (θ _{IA})								
so			75			*		°C/W

^{*} Same as specification for ADS7809U.

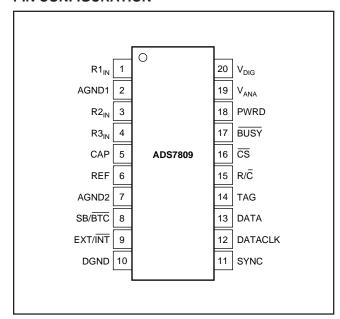
NOTES: (1) LSB means Least Significant Bit. For the $\pm 10 V$ input range, one LSB is $305 \mu V$.

- (2) Typical rms noise at worst case transitions and temperatures.
- (3) As measured with fixed resistors shown in Figure 4. Adjustable to zero with external potentiometer.
- (4) For bipolar input ranges, full-scale error is the worst case of –Full Scale or +Full Scale untrimmed deviation from ideal first and last code transitions, divided by the transition voltage (not divided by the full-scale range) and includes the effect of offset error. For unipolar input ranges, full-scale error is the deviation of the last code transition divided by the transition voltage. It also includes the effect of offset error.
- (5) All specifications in dB are referred to a full-scale $\pm 10 \text{V}$ input.
- (6) Full-Power Bandwidth defined as Full-Scale input frequency at which Signal-to-(Noise + Distortion) degrades to 60dB.
- (7) Recovers to specified performance after 2 FS input overvoltage.
- (8) The minimum $\rm V_{IH}$ level for the DATACLK signal is 3V.

PIN ASSIGNMENTS

PIN#	NAME	DESCRIPTION
1	R1 _{IN}	Analog Input. See Table I and Figure 4 for input range connections.
2	AGND1	Analog Ground. Used internally as ground reference point. Minimal current flow.
3	R2 _{IN}	Analog Input. See Table I and Figure 4 for input range connections.
4	R3 _{IN}	Analog Input. See Table I and Figure 4 for input range connections.
5	CAP	Reference Buffer Capacitor. 2.2μF Tantalum to ground.
6	REF	Reference Input/Output. Outputs internal 2.5V reference. Can also be driven by external system reference. In both cases, bypass to ground with a 2.2μF Tantalum capacitor.
7	AGND2	Analog Ground
8	SB/BTC	Select Straight Binary or Binary Two's Complement data output format. If HIGH, data will be output in a Straight Binary format. If LOW, data will be output in a Binary Two's Complement format.
9	EXT/INT	Select External or Internal Clock for transmitting data. If HIGH, data will be output synchronized to the clock input on DATACLK. If LOW, a convert command will initiate the transmission of the data from the previous conversion, along with 16 clock pulses output on DATACLK.
10	DGND	Digital Ground
11	SYNC	Synch Output. If EXT/INT is HIGH, either a rising edge on R/C with CS LOW or a falling edge on CS with R/C HIGH will output a pulse on SYNC synchronized to the external DATACLK.
12	DATACLK	Either an input or an output depending on the EXT/INT level. Output data will be synchronized to this clock. If EXT/INT is LOW, DATACLK will transmit 16 pulses after each conversion, and then remain LOW between conversions.
13	DATA	Serial Data Output. Data will be synchronized to DATACLK, with the format determined by the level of SB/BTC. In the external clock mode, after 16 bits of data, the ADS7809 will output the level input on TAG as long as \overline{CS} is LOW and R/\overline{C} is HIGH (see Figure 3). If EXT/ \overline{INT} is LOW, data will be valid on both the rising and falling edges of DATACLK, and between conversions DATA will stay at the level of the TAG input when the conversion was started.
14	TAG	Tag Input for use in external clock mode. If EXT/INT is HIGH, digital data input on TAG will be output on DATA with a delay of 16 DATACLK pulses as long as $\overline{\text{CS}}$ is LOW and R/ $\overline{\text{C}}$ is HIGH. See Figure 3.
15	R/C	Read/Convert Input. With $\overline{\text{CS}}$ LOW, a falling edge on R/ $\overline{\text{C}}$ puts the internal sample-and-hold into the hold state and <u>sta</u> rts a conversion. When EXT/ $\overline{\text{INT}}$ is LOW, this also initiates the transmission of the data results from the previous conversion. If EXT/ $\overline{\text{INT}}$ is HIGH, a rising edge on R/ $\overline{\text{C}}$ with $\overline{\text{CS}}$ LOW, or a falling edge on $\overline{\text{CS}}$ with R/ $\overline{\text{C}}$ HIGH, transmits a pulse on SYNC and initiates the transmission of data from the previous conversion.
16	<u>cs</u>	Chip Select. Internally OR'ed with R/C.
17	BUSY	Busy Output. Falls when a conversion is started, and remains LOW until the conversion is completed and the data is latched into the output shift register. \overline{CS} or R/\overline{C} must be HIGH when \overline{BUSY} rises, or another conversion will start without time for signal acquisition.
18	PWRD	Power Down Input. If HIGH, conversions are inhibited and power consumption is significantly reduced. Results from the previous conversion are maintained in the output shift register.
19	V_{ANA}	Analog Supply Input. Nominally +5V. Connect directly to pin 20, and decouple to ground with 0.1μF ceramic and 10μF tantalum capacitors.
20	V_{DIG}	Digital Supply Input. Nominally +5V. Connect directly to pin 19. Must be $\leq V_{ANA}$.

PIN CONFIGURATION



ANALOG INPUT RANGE	$\begin{array}{c} \text{CONNECT R1}_{\text{IN}} \\ \text{VIA 200} \Omega \\ \text{TO} \end{array}$	$\begin{array}{c} \textbf{CONNECT R2}_{\textbf{IN}} \\ \textbf{VIA 100} \Omega \\ \textbf{TO} \end{array}$	CONNECT R3 _{IN} TO	IMPEDANCE
±10V	V _{IN}	AGND	CAP	22.9kΩ
±5V	AGND	V _{IN}	CAP	13.3kΩ
±3.33V	V _{IN}	V _{IN}	CAP	10.7kΩ
0V to 10V	AGND	V _{IN}	AGND	13.3kΩ
0V to 5V	AGND	AGND	V _{IN}	10.0kΩ
0V to 4V	V_{IN}	AGND	V _{IN}	10.7kΩ

TABLE I. Input Range Connections. See Figure 4 for complete information.

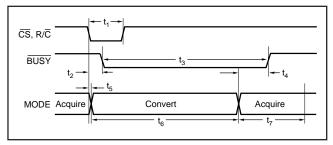


FIGURE 1. Basic Conversion Timing.

SYMBOL	DESCRIPTION	MIN	TYP	MAX	UNITS
t ₁	Convert Pulse Width	40		6000	ns
t ₂	BUSY Delay			65	ns
t ₃	BUSY LOW			8	μs
t ₄	BUSY Delay After End of Conversion		220		ns
t ₅	Aperture Delay		40		ns
t ₆	Conversion Time		7.6	8	μs
t ₇	Acquisition Time			2	μs
$t_6 + t_7$	Throughput Time		9	10	μs
t ₈	R/C LOW to DATACLK Delay		450		ns
t ₉	DATACLK Period		440		ns
t ₁₀	Data Valid to DATACLK HIGH Delay	20	75		ns
t ₁₁	Data Valid After DATACLK LOW Delay	100	125		ns
t ₁₂	External DATACLK	100			ns
t ₁₃	External DATACLK HIGH	20			ns
t ₁₄	External DATACLK LOW	30			ns
t ₁₅	DATACLK HIGH Setup Time	20		t ₁₂ + 5	ns
t ₁₆	R/C to CS Setup Time	10			ns
t ₁₇	SYNC Delay After DATACLK HIGH	15		35	ns
t ₁₈	Data Valid Delay	25		55	ns
t ₁₉	CS to Rising Edge Delay	25			ns
t ₂₀	Data Available after CS LOW	6			μs

TABLE II. Conversion and Data Timing. $T_A = -40^{\circ}C$ to +85°C.

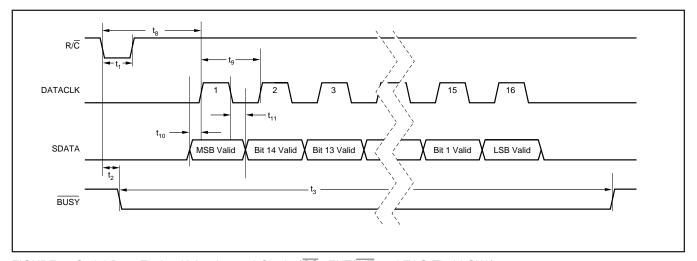


FIGURE 2. Serial Data Timing Using Internal Clock. ($\overline{\text{CS}}$, EXT/ $\overline{\text{INT}}$ and TAG Tied LOW.)

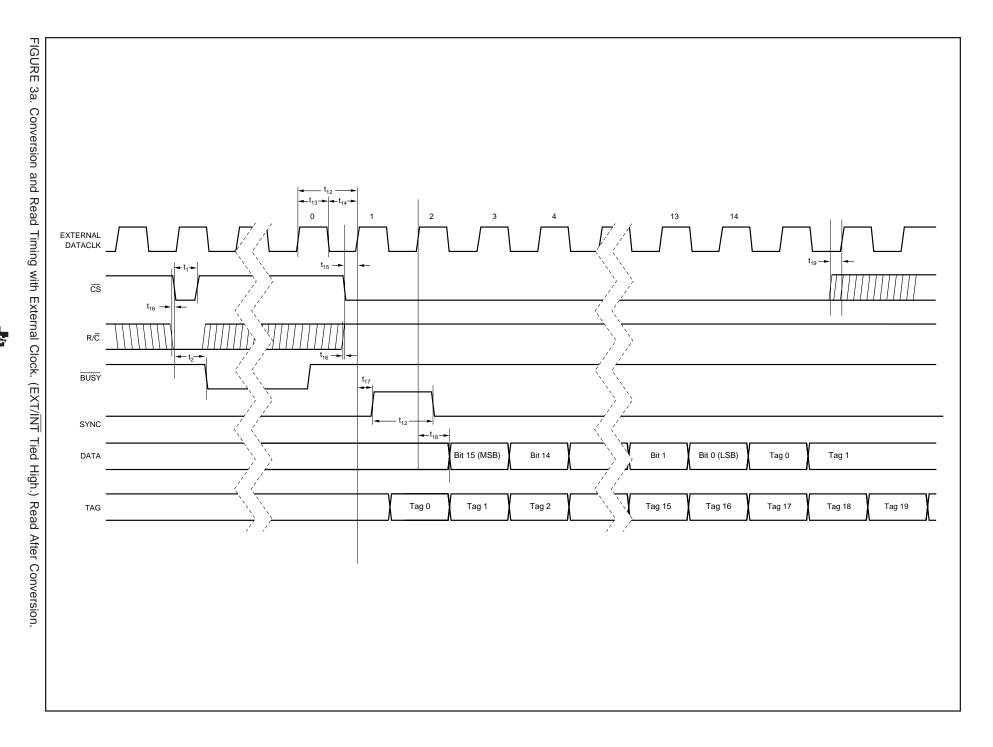
SPECIFIC FUNCTION	cs	R/C	BUSY	EXT/INT	DATACLK	PWRD	SB/BTC	OPERATION
Initiate Conversion and Output Data Using Internal Clock	1 > 0	0	1	0	Output	0	х	Initiates conversion "n". Data from conversion "n – 1" clocked out on DATA synchronized to 16 clock pulses output on DATACLK.
	0	1 > 0	1	0	Output	0	х	Initiates conversion "n". Data from conversion "n – 1" clocked out on DATA synchronized to 16 clock pulses output on DATACLK.
Initiate Conversion and	1 > 0	0	1	1	Input	0	х	Initiates conversion "n".
Output Data Using External	0	1 > 0	1	1	Input	0	х	Initiates conversion "n".
Clock	1 > 0	1	1	1	Input	x	х	Outputs a pulse on SYNC followed by data from conversion "n" clocked out synchronized to external DATACLK.
	1 > 0	1	0	1	Input	0	х	Outputs a pulse on SYNC followed by data from conversion "n – 1" clocked out synchronized to external DATACLK. ⁽¹⁾ Conversion "n" in process.
	0	0 > 1	0	1	Input	0	х	Outputs a pulse on SYNC followed by data from conversion "n – 1" clocked out synchronized to external DATACLK . ⁽¹⁾ Conversion "n" in process.
Incorrect Conversions	0	0	0 > 1	х	х	0	х	CS or R/C must be HIGH or a new conversion will be initiated without time for acquisition.
Power-Down	х	Х	х	Х	Х	0	х	Analog circuitry powered. Conversion can proceed.
	x	х	х	х	x	1	х	Analog circuitry disabled. Data from previous conversion maintained in output registers.
Selecting Output Format	х	х	х	х	х	х	0	Serial data is output in Binary Two's Complement format.
- '	×	×	x	x	×	x	1	Serial data is output in Straight Binary format.

TABLE III. Control Truth Table.

							DI	GITAL O	UTPUT	
						BINARY TWO'S COMP (SB/BTC LOW)	STRAIGHT BINARY (SB/BTC HIGH)			
DESCRIPTION		AN	IALOG INPL	JT			BINARY CODE	HEX CODE	BINARY CODE	HEX CODE
Full-Scale Range	±10	±5	±3.33V	0V to 10V	0V to 5V	0V to 4V				
Least Significant Bit (LSB)	305μV	153μV	102μV	153μV	76μV	61μV				
+Full Scale (FS - 1LSB)	9.999695V	4.999847V	3.333231V	9.999847V	4.999924V	3.999939V	0111 1111 1111 1111	7FFF	1111 1111 1111 1111	FFFF
Midscale	0V	0V	0V	5V	2.5V	2V	0000 0000 0000 0000	0000	1000 0000 0000 0000	8000
One LSB Below Midscale	–305μV	–153μV	–102μV	4.999847V	2.499924V	1.999939V	1111 1111 1111 1111	FFFF	0111 1111 1111 1111	7FFF
-Full Scale	-10V	-5V	-3.333333V	0V	0V	0V	1000 0000 0000 0000	8000	0000 0000 0000 0000	0000

TABLE IV. Output Codes and Ideal Input Voltages.





INSTRUMENTS
www.ti.com

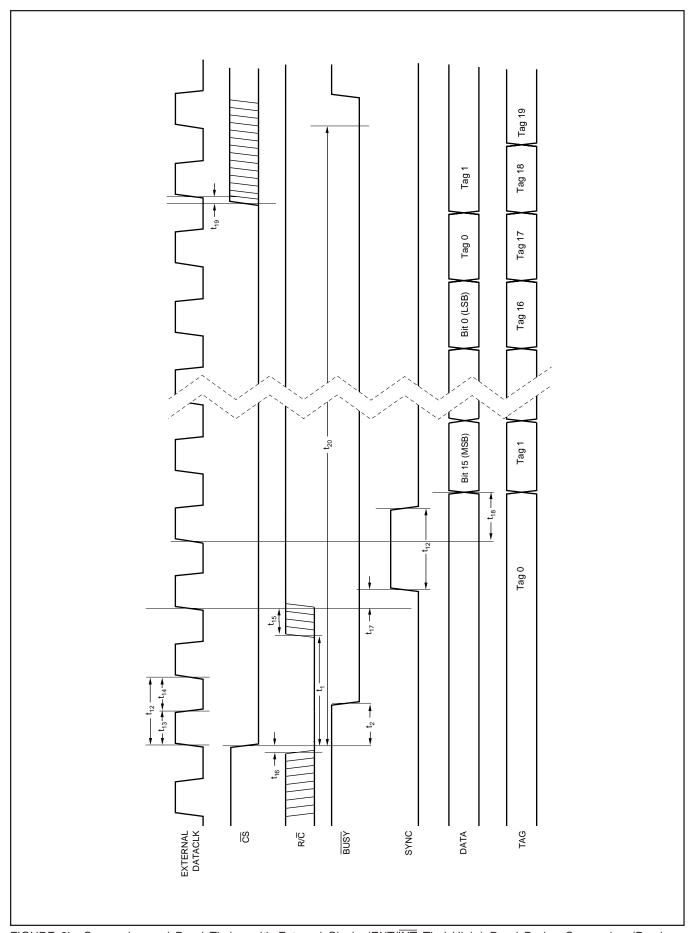


FIGURE 3b. Conversion and Read Timing with External Clock. (EXT/INT Tied High.) Read During Conversion (Previous Conversion Results).

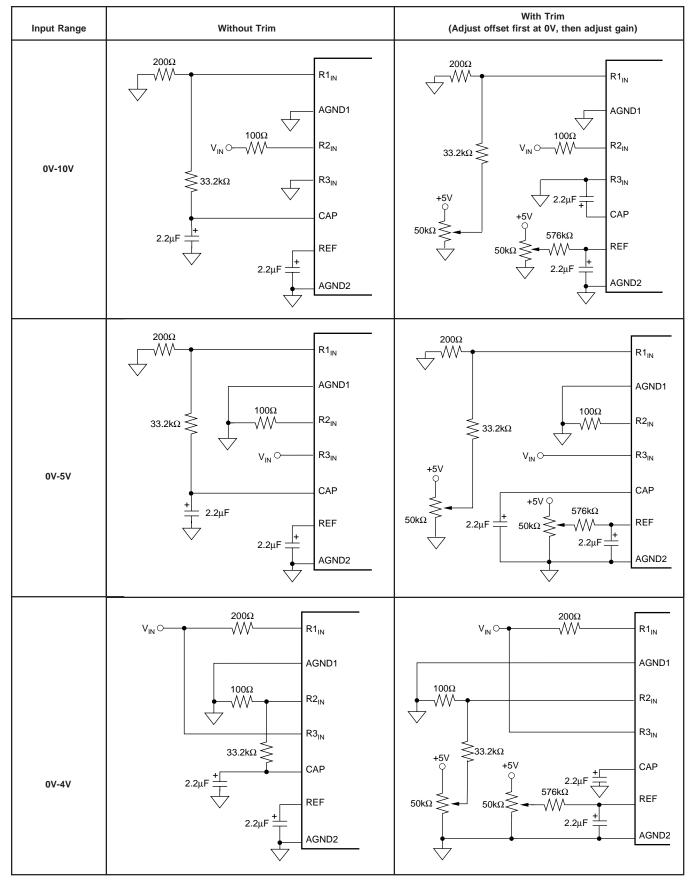


FIGURE 4a. Offset/Gain Circuits for Unipolar Input Ranges.

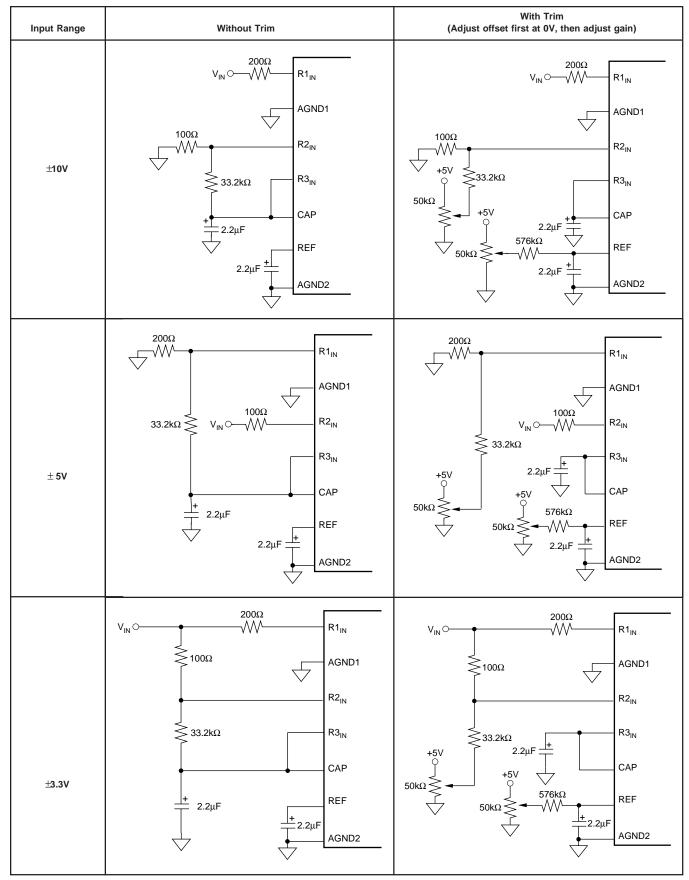


FIGURE 4b. Offset/Gain Circuits for Bipolar Input Ranges.

Revision History

DATE	REVISION	PAGE	SECTION	DESCRIPTION
10/06	С	3	Absolute Maximum Ratings	CAP and REF were switched.

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.



www.ti.com 1-Dec-2023

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
ADS7809U	LIFEBUY	SOIC	DW	20	25	RoHS & Green	Call TI	Level-3-260C-168 HR	-40 to 85	ADS7809U	
ADS7809U/1K	LIFEBUY	SOIC	DW	20	1000	RoHS & Green	Call TI	Level-3-260C-168 HR	-40 to 85	ADS7809U	
ADS7809U/1KE4	LIFEBUY	SOIC	DW	20	1000	RoHS & Green	Call TI	Level-3-260C-168 HR	-40 to 85	ADS7809U	
ADS7809UB	LIFEBUY	SOIC	DW	20	25	RoHS & Green	Call TI	Level-3-260C-168 HR	-40 to 85	ADS7809U B	
ADS7809UB/1K	LIFEBUY	SOIC	DW	20	1000	RoHS & Green	Call TI	Level-3-260C-168 HR	-40 to 85	ADS7809U B	
ADS7809UE4	LIFEBUY	SOIC	DW	20	25	RoHS & Green	Call TI	Level-3-260C-168 HR	-40 to 85	ADS7809U	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.



PACKAGE OPTION ADDENDUM

www.ti.com 1-Dec-2023

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

www.ti.com 5-Jan-2022

TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

	Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
I	ADS7809U/1K	SOIC	DW	20	1000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
I	ADS7809UB/1K	SOIC	DW	20	1000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

www.ti.com 5-Jan-2022



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ADS7809U/1K	SOIC	DW	20	1000	367.0	367.0	45.0
ADS7809UB/1K	SOIC	DW	20	1000	367.0	367.0	45.0

PACKAGE MATERIALS INFORMATION

www.ti.com 5-Jan-2022

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
ADS7809U	DW	SOIC	20	25	507	12.83	5080	6.6
ADS7809UB	DW	SOIC	20	25	507	12.83	5080	6.6
ADS7809UE4	DW	SOIC	20	25	507	12.83	5080	6.6



SOIC



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2023, Texas Instruments Incorporated